

ABSTRACT OF THE DISCLOSURE

Semiconductor chips are connected to electrode terminals (6a, 6b) by wire bonding, and connecting conductors connect extending portions (60b, 60c) extending
5 from a part of the electrode terminals (6b, 6c) to the circuit patterns (3a, 3b) by soldering, and thus the wire bonding points of the electrode terminals are reduced to thereby reduce an electric resistance and suppress heat generation and voltage drop.